



3.2mmx1.6mm SMD CHIP LED LAMP

Features

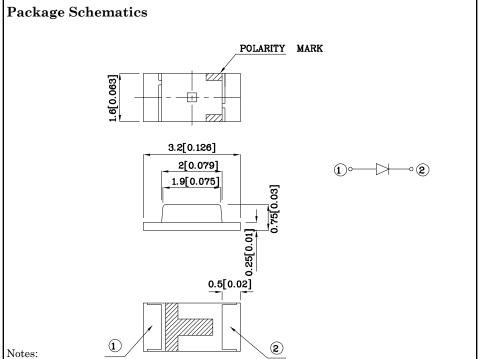
- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- \bullet MSL (Moisture Sensitivity Level): 3
- RoHS compliant







ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)			
V_{R}	5	V	
I_{F}	30	mA	
i_{FS}	100	mA	
P_{D}	120	mW	
T_{A}	-40 ~ +85	°C	
Tstg	-40 ~ +85	-0	
Electrostatic Discharge Threshold (HBM)		V	
	I_{F} i_{FS} P_{D} T_{A} $Tstg$	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

XZFBB55W-1

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Operating Characteristics (T _A =25°C)		Blue (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	$V_{ m F}$	3.3	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4	V
Reverse Current (Max.) (V _R =5V)	I_R	50	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λΡ	465*	nm
Wavelength of Dominant EmissionCIE127-2007* (Typ.) (I _F =20mA)	λD	470*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\triangle \lambda$	22	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	100	pF

178*

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =20mA) mcd	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min. typ.		

Water Clear

120*

InGaN

Blue

465*

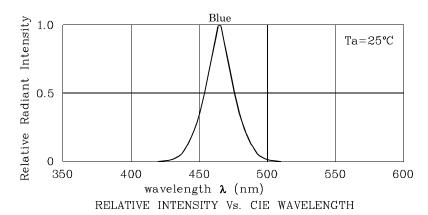
 150°

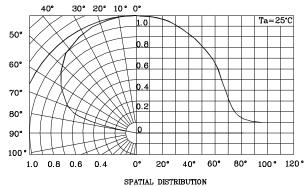
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



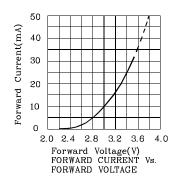


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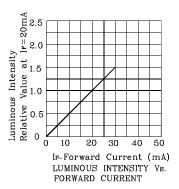


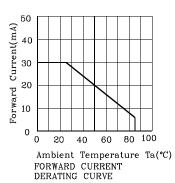


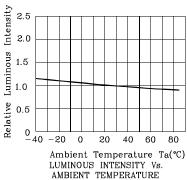
♦ Blue



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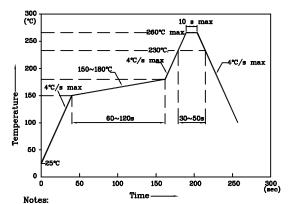






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

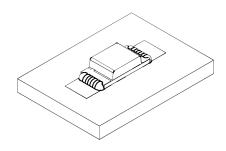


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- Do not put stress to the epoxy resin during high temperatures conditions

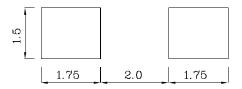




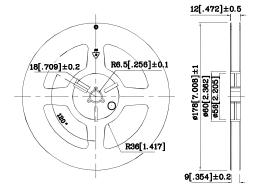
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



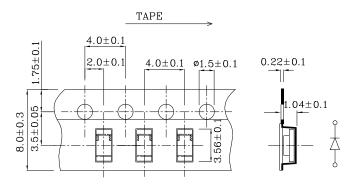
♦ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

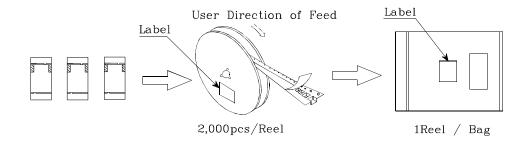
Note: Accuracy may depend on the sorting parameters.

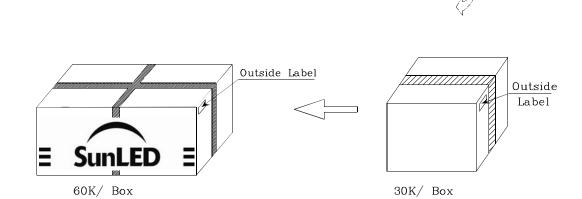
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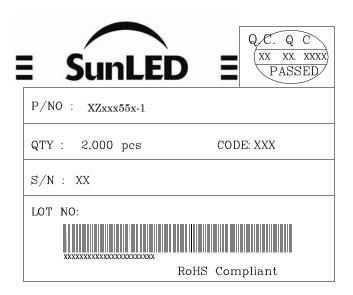


PACKING & LABEL SPECIFICATIONS

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